WHAT IS CLAIMED IS:

1. A semiconductor device having a pad with which a terminal is brought into contact upon inspection or measurement of electric properties of a semiconductor element, wherein

a first conductor and a second conductor are arranged at a surface of said pad,

said first conductor has hardness that is greater than hardness of said second conductor and not lower than hardness of said terminal , and

said first conductor is arranged at the surface of said pad such that said terminal hits against said first conductor at least one time while said terminal is in contact with and sliding on the surface of said pad.

2. The semiconductor device having a pad according to claim 1, wherein a plurality of said first conductors are arranged in the form of an array at the surface of said pad.

3. The semiconductor device having a pad according to claim 1, wherein a plurality of said first conductors are arranged in the form of slits at the surface of said pad.

4. The semiconductor device having a pad according to claim 1, wherein a plurality of said first conductors are distributed at random over the surface of said pad.

5. The semiconductor device having a pad according to claim 1, wherein said pad has said first conductor as its main body, and said second conductor is arranged at a surface of said first conductor.

6. The semiconductor device having a pad according to claim 1, wherein said first conductor is formed of a material containing at least one kind selected from a group consisting of tungsten, tungsten alloy, titanium alloy, rhenium, nickel and nickel alloy, and said second conductor is formed of a material containing aluminum.